



Material Composition

Product GS9076CNE3
Package QFN 64L 9 x 9 x 0.9
Manufacturer Gennum Corporation

Date 23/01/2008

Component	BOM Item	Weight Component mg	Substance	Weight of Substance mg	Homogeneous material	
					%	ppm
Leadframe	Olin 7025	117.14	Cu	112.69	96.20	962000
			Ni	3.51	3.00	30000
			Si	0.76	0.65	6500
			Mg	0.18	0.15	1500
			Sub-total	117.14	100.00	1000000
Mold compound	EME G770HC	102.55	Silica Fused	86.14	84.00	840000
			Epoxy Resin 1	4.61	4.50	45000
			Epoxy resin 2	4.61	4.50	45000
			Phenol resin	4.61	4.50	45000
			Metal Hydroxide	2.05	2.00	20000
			Carbon Black	0.51	0.50	5000
			Sub-total	102.55	100.00	1000000
Chip		7.25	Si	7.21	99.40	994000
			Al	0.04	0.60	6000
			Sub-total	7.25	100.00	1000000
Die Attach	CRM1076DS	1.20	Ag	0.91	76.00	760000
			Epoxy Resin t-Butylphenyl glycidylether	0.16	13.00	130000
				0.08	7.00	70000
			Phenolic resin	0.03	2.80	28000
			Epoxy silane	0.01	1.20	12000
Sub-total	1.20	100.00	1000000			
Wire	AW88	1.76	Au	1.76	99.99	999900
External Lead Finish		5.26	Sn	5.26	100.00	1000000
Internal Pad Finish		0.50	Ag	0.50	100.00	1000000
Total		235.66				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5
 Tel. +(905)632-2996 Fax.+1(905)632-5946

www.gennum.com

The information contained in this document describes the homogeneous material composition of this product according to the definition set forth in the EU RoHS Directive 2002/95/EC. This information may have been derived from calculations based on information obtained from our suppliers. Gennum Corporation assumes no liability for any errors or omissions in this document. Gennum reserves the right to make any changes to this document at any time without notice.